

**100V N-CHANNEL ENHANCEMENT MODE MOSFET**

**Product Summary**

| $V_{(BR)DSS}$ | $R_{DS(ON)}$                   | Package         | Max $I_D$<br>$T_A = +25^\circ C$ |
|---------------|--------------------------------|-----------------|----------------------------------|
| 100V          | 125m $\Omega$ @ $V_{GS} = 10V$ | TO252<br>(DPAK) | 6.4A                             |
|               | 150m $\Omega$ @ $V_{GS} = 6V$  |                 | 5.8A                             |

**Description**

This MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

**Applications**

- DC-DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control

**Features**

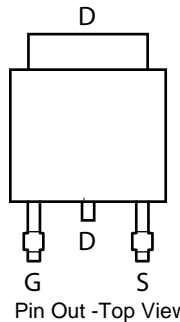
- Low On-Resistance
- Fast Switching Speed
- Low Gate Drive
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

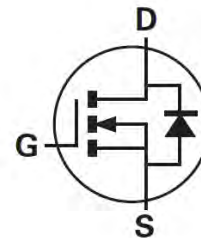
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.33 grams (approximate)



Top View



Pin Out -Top View



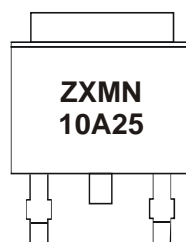
Equivalent Circuit

**Ordering Information (4 & 5)**

| Part Number  | Marking   | Reel size (inches) | Tape width (mm) | Quantity per reel |
|--------------|-----------|--------------------|-----------------|-------------------|
| ZXMN10A25KTC | ZXMN10A25 | 13                 | 16              | 2,500             |

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For Packaging Details, go to our website at <http://www.diodes.com>.
  5. Products with Q-suffix are automotive grade. Automotive products are electrical and thermal the same as the commercial, except where specified.

**Marking Information**



ZXMN10A25 = Product Type Marking Code

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

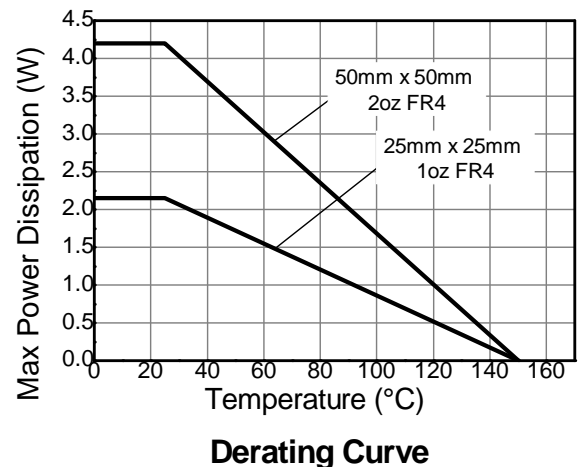
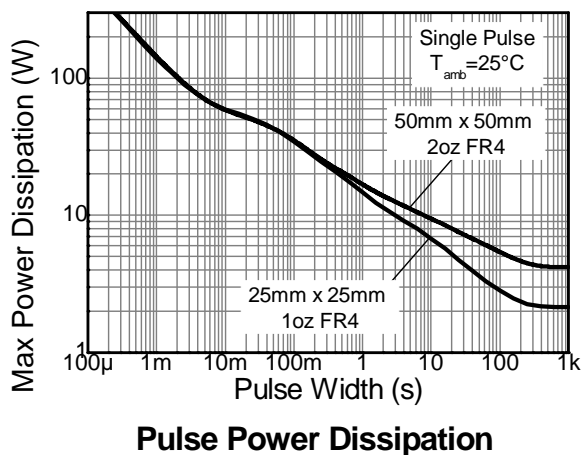
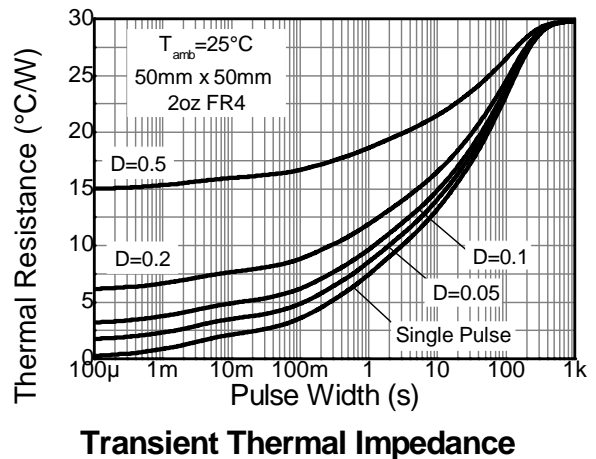
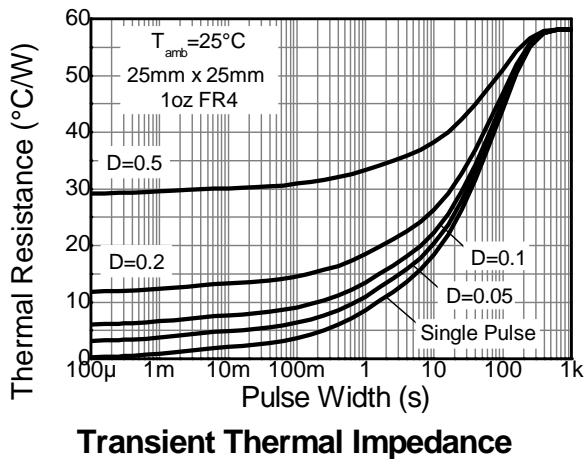
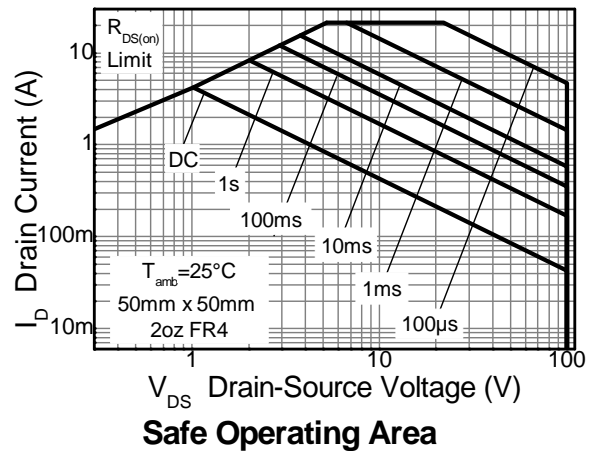
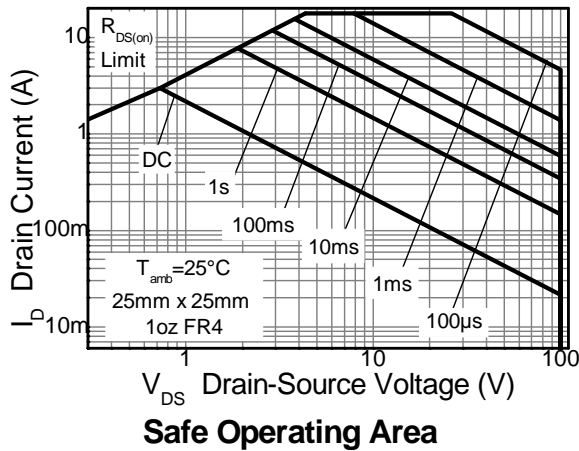
| Characteristic                         |                       | Symbol                          | Value | Unit |
|--|-----------------------|---------------------------------|-------|------|
| Drain-Source voltage                   |                       | V <sub>DSS</sub>                | 100   | V    |
| Gate-Source voltage                    |                       | V <sub>GS</sub>                 | ±20   | V    |
| Continuous Drain current               | V <sub>GS</sub> = 10V | (Note 7)                        | 6.4   | A    |
|  |                       | T <sub>A</sub> = +70°C (Note 7) | 5     |      |
|  |                       | (Note 6)                        | 4.2   |      |
| Pulsed Drain current                   |                       | I <sub>DM</sub>                 | 21    | A    |
| Continuous Source current (Body diode) |                       | I <sub>S</sub>                  | 10    | A    |
| Pulsed Source current (Body diode)     |                       | I <sub>SM</sub>                 | 21    | A    |

**Thermal Characteristics**

| Characteristic                              |          | Symbol                            | Value      | Unit       |
|---|----------|-----------------------------------|------------|------------|
| Power dissipation<br>Linear derating factor | (Note 6) | P <sub>D</sub>                    | 4.25       | W<br>mW/°C |
|   |          |                                   | 34         |            |
|   | (Note 7) |                                   | 9.85       |            |
|   |          |                                   | 78.7       |            |
| Thermal Resistance, Junction to Ambient     | (Note 9) | R <sub>θJA</sub>                  | 2.11       | °C/W       |
|   |          |                                   | 16.8       |            |
|   | (Note 6) |                                   | 29.4       |            |
|   | (Note 7) |                                   | 12.7       |            |
| Thermal Resistance, Junction to Lead        | (Note 9) | R <sub>θJL</sub>                  | 59.1       |            |
| Operating and storage temperature range     |          | T <sub>J</sub> , T <sub>STG</sub> | -55 to 150 | °C         |

- Notes:
6. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  7. For a device surface mounted on FR4 PCB measured at t ≤ 10 sec.
  8. Repetitive rating 50mm x 50mm x 1.6mm FR4 PCB, D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
  9. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  10. Thermal resistance from junction to solder-point (at the end of the drain lead).

**Thermal Characteristics**

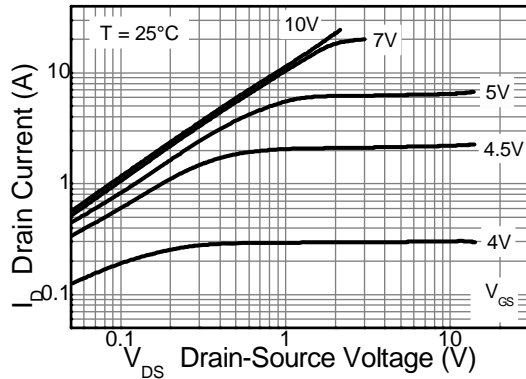


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

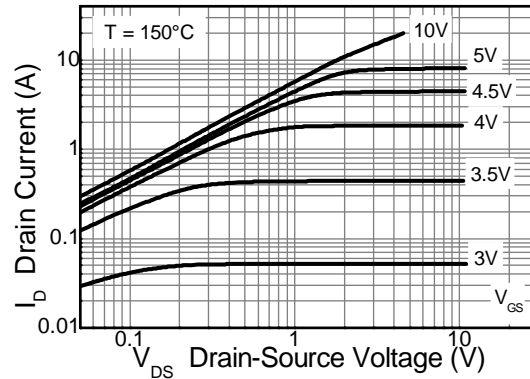
| Characteristic                              | Symbol              | Min | Typ   | Max  | Unit | Test Condition   |  |
|---|---------------------|-----|-------|------|------|--|--|
| <b>OFF CHARACTERISTICS</b>                  |                     |     |       |      |      |  |  |
| Drain-Source Breakdown Voltage              | BV <sub>DSS</sub>   | 100 | —     | —    | V    | I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V   |  |
| Zero Gate Voltage Drain Current             | I <sub>DSS</sub>    | —   | —     | 0.5  | μA   | V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V   |  |
| Gate-Source Leakage                         | I <sub>GSS</sub>    | —   | —     | ±100 | nA   | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V   |  |
| <b>ON CHARACTERISTICS</b>                   |                     |     |       |      |      |  |  |
| Gate Threshold Voltage                      | V <sub>GS(th)</sub> | 2.0 | —     | 4.0  | V    | I <sub>D</sub> = 250μA, V <sub>DS</sub> = V <sub>GS</sub>                                  |  |
| Static Drain-Source On-Resistance (Note 11) | R <sub>DS(on)</sub> | —   | —     | 125  | mΩ   | V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.2A   |  |
|   |                     |     |       | 150  |      | V <sub>GS</sub> = 6V, I <sub>D</sub> = 2.6A  |  |
| Forward Transconductance (Notes 11 & 12)    | g <sub>fs</sub>     | —   | 7.3   | —    | S    | V <sub>DS</sub> = 15V, I <sub>D</sub> = 2.9A   |  |
| Diode Forward Voltage (Note 11)             | V <sub>SD</sub>     | —   | 0.85  | 0.95 | V    | I <sub>S</sub> = 3.2A, V <sub>GS</sub> = 0V, T <sub>J</sub> = +25°C                        |  |
| Reverse recovery time (Note 12)             | t <sub>rr</sub>     | —   | 40.5  | —    | ns   | I <sub>S</sub> = 2.9A, di/dt = 100A/μs   |  |
| Reverse recovery charge (Note 12)           | Q <sub>rr</sub>     | —   | 62    | —    | nC   | T <sub>J</sub> = +25°C   |  |
| <b>DYNAMIC CHARACTERISTICS (Note 12)</b>    |                     |     |       |      |      |  |  |
| Input Capacitance                           | C <sub>iss</sub>    | —   | 859   | —    | pF   | V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V<br>f = 1MHz                                    |  |
| Output Capacitance                          | C <sub>oss</sub>    | —   | 57.3  | —    | pF   |  |  |
| Reverse Transfer Capacitance                | C <sub>rss</sub>    | —   | 33    | —    | pF   |  |  |
| Total Gate Charge (Note 13)                 | Q <sub>g</sub>      | —   | 9.6   | —    | nC   | V <sub>GS</sub> = 5V   | V <sub>DS</sub> = 50V<br>I <sub>D</sub> = 2.9A |
| Total Gate Charge (Note 13)                 | Q <sub>g</sub>      | —   | 17.16 | —    | nC   | V <sub>GS</sub> = 10V  |  |
| Gate-Source Charge (Note 13)                | Q <sub>gs</sub>     | —   | 3.77  | —    | nC   |  |  |
| Gate-Drain Charge (Note 13)                 | Q <sub>gd</sub>     | —   | 5.36  | —    | nC   |  |  |
| Turn-On Delay Time (Note 13)                | t <sub>D(on)</sub>  | —   | 4.9   | —    | ns   | V <sub>DD</sub> = 50V, V <sub>GS</sub> = 10V<br>I <sub>D</sub> = 1A, R <sub>G</sub> ≅ 6.0Ω |  |
| Turn-On Rise Time (Note 13)                 | t <sub>r</sub>      | —   | 3.7   | —    | ns   |  |  |
| Turn-Off Delay Time (Note 13)               | t <sub>D(off)</sub> | —   | 17.7  | —    | ns   |  |  |
| Turn-Off Fall Time (Note 13)                | t <sub>f</sub>      | —   | 9.4   | —    | ns   |  |  |

- Notes: 11. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%  
 12. For design aid only, not subject to production testing.  
 13. Switching characteristics are independent of operating junction temperatures.

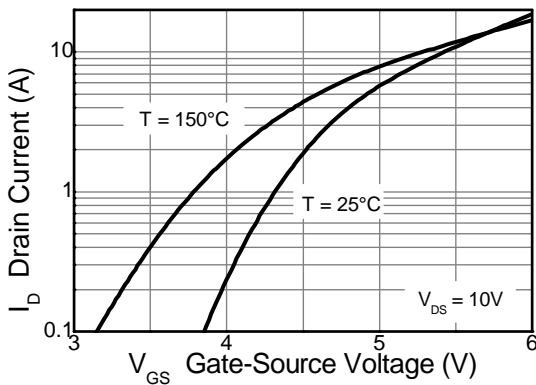
**Typical Characteristics**



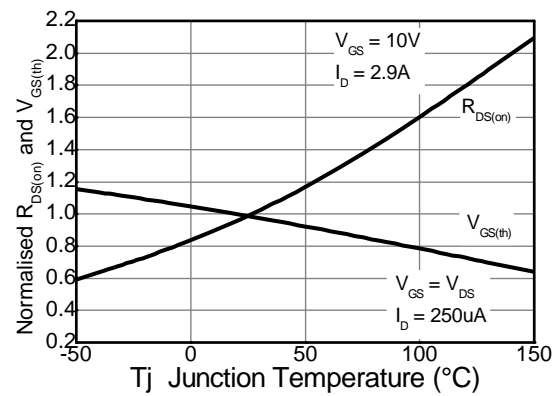
**Output Characteristics**



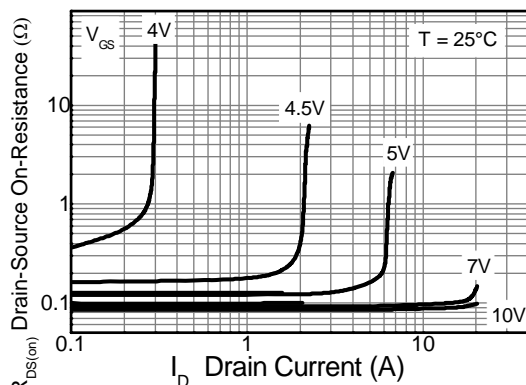
**Output Characteristics**



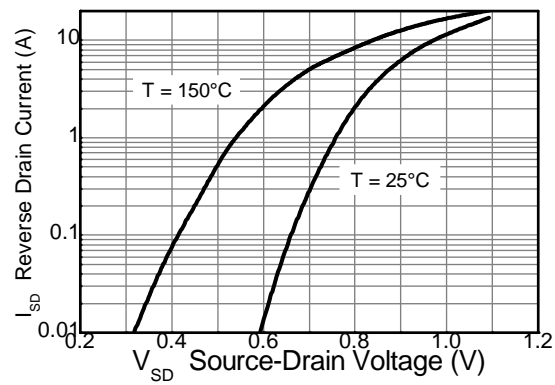
**Typical Transfer Characteristics**



**Normalised Curves v Temperature**

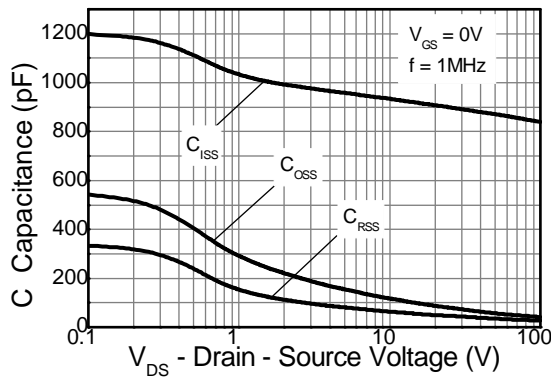


**On-Resistance v Drain Current**

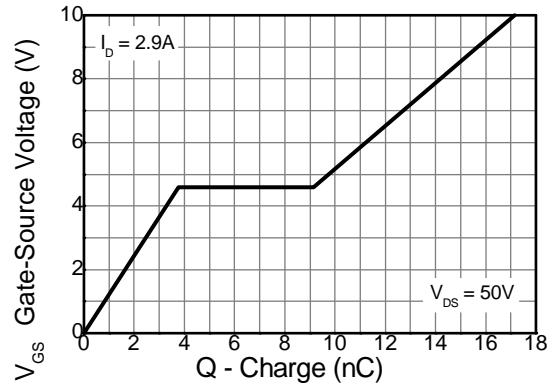


**Source-Drain Diode Forward Voltage**

**Typical Characteristics (cont.)**

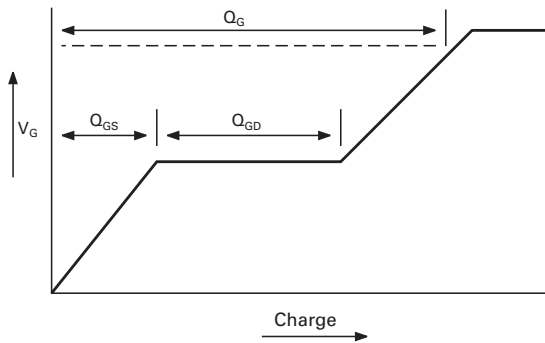


**Capacitance v Drain-Source Voltage**

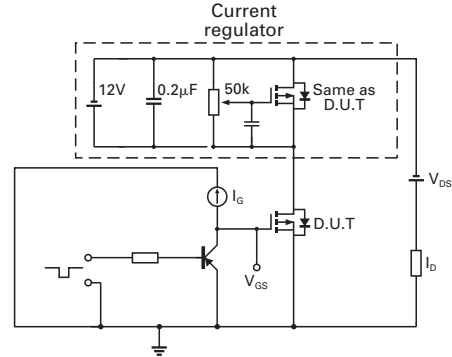


**Gate-Source Voltage v Gate Charge**

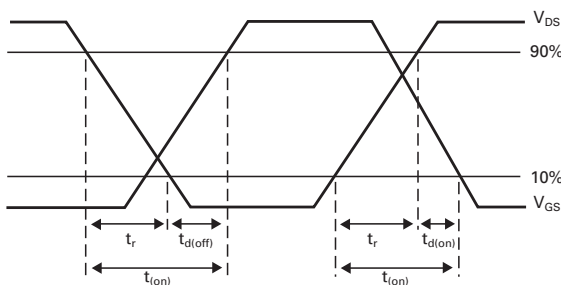
**Test Circuits**



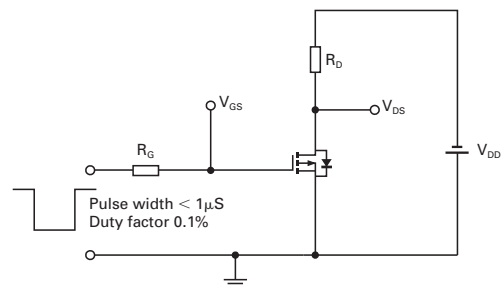
**Basic gate charge waveform**



**Gate charge test circuit**

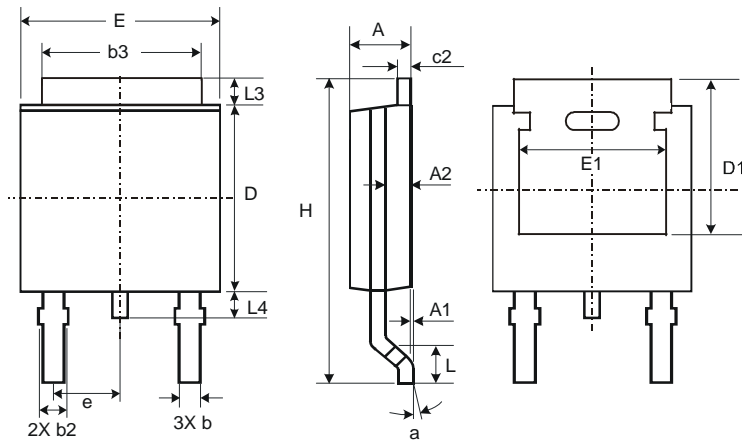


**Switching time waveforms**



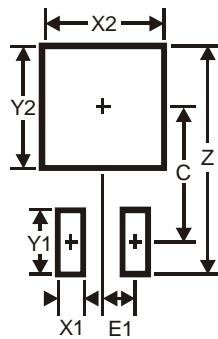
**Switching time test circuit**

**Package Outline Dimensions**



| TO252                |      |       |       |
|----------------------|------|-------|-------|
| Dim                  | Min  | Max   | Typ   |
| A                    | 2.19 | 2.39  | 2.29  |
| A1                   | 0.00 | 0.13  | 0.08  |
| A2                   | 0.97 | 1.17  | 1.07  |
| b                    | 0.64 | 0.88  | 0.783 |
| b2                   | 0.76 | 1.14  | 0.95  |
| b3                   | 5.21 | 5.46  | 5.33  |
| c2                   | 0.45 | 0.58  | 0.531 |
| D                    | 6.00 | 6.20  | 6.10  |
| D1                   | 5.21 | -     | -     |
| e                    | -    | -     | 2.286 |
| E                    | 6.45 | 6.70  | 6.58  |
| E1                   | 4.32 | -     | -     |
| H                    | 9.40 | 10.41 | 9.91  |
| L                    | 1.40 | 1.78  | 1.59  |
| L3                   | 0.88 | 1.27  | 1.08  |
| L4                   | 0.64 | 1.02  | 0.83  |
| a                    | 0°   | 10°   | -     |
| All Dimensions in mm |      |       |       |

**Suggested Pad Layout**



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 11.6          |
| X1         | 1.5           |
| X2         | 7.0           |
| Y1         | 2.5           |
| Y2         | 7.0           |
| C          | 6.9           |
| E1         | 2.3           |

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